

2024 IEEE Electrical Design of Advanced Packaging and Systems (EDAPS 2024)

**Bangalore, India
17-19 December 2024**



**IEEE Catalog Number: CFP24EDP-POD
ISBN: 979-8-3315-4326-6**

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IEEE Catalog Number:	CFP24EDP-POD
ISBN (Print-On-Demand):	979-8-3315-4326-6
ISBN (Online):	979-8-3315-4325-9
ISSN:	2151-1225

Additional Copies of This Publication Are Available From:

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